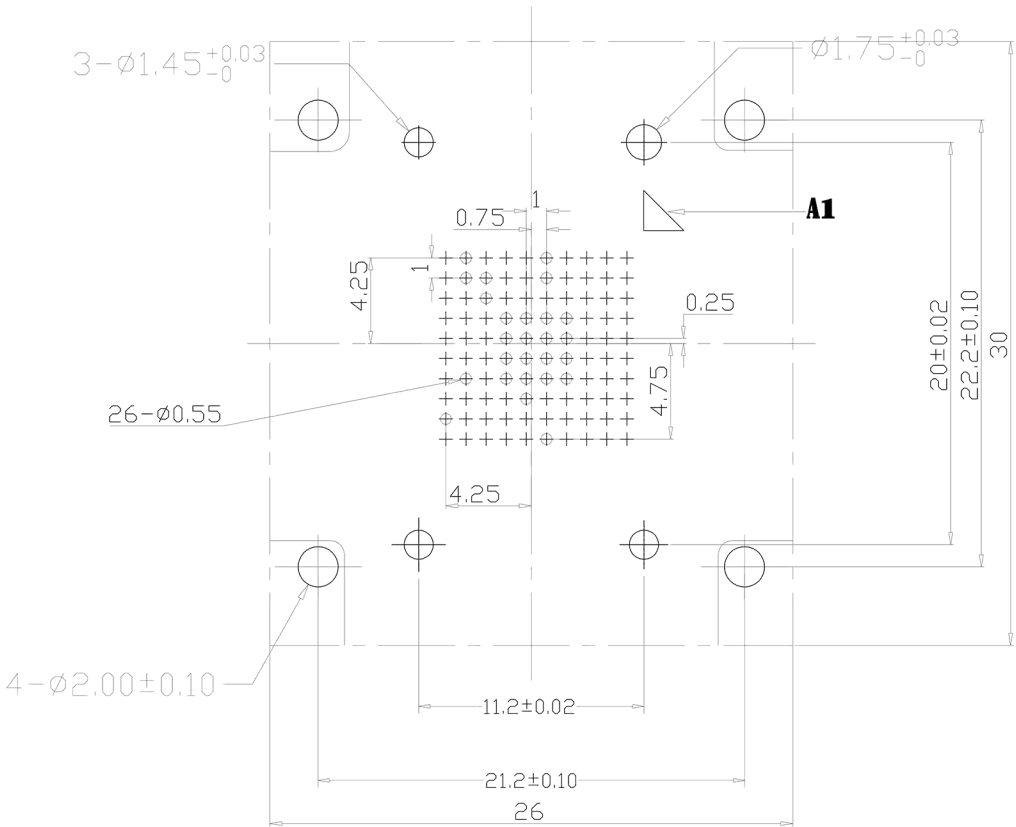
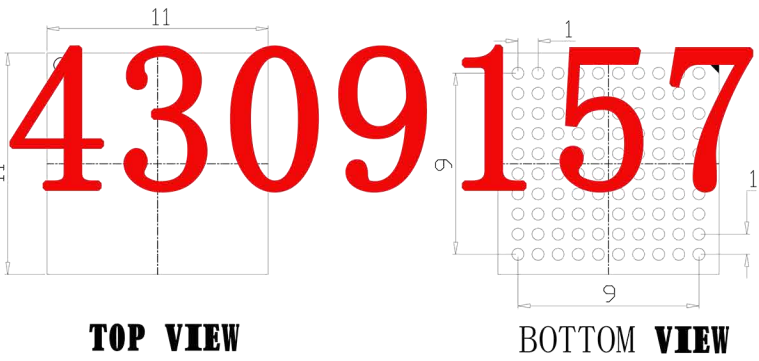


REVISION	DESCRIPTION	CHECK	APP	DATE	REV. NOTICE. NO
1					
2					
3					

PCB Pattern(TOP View)



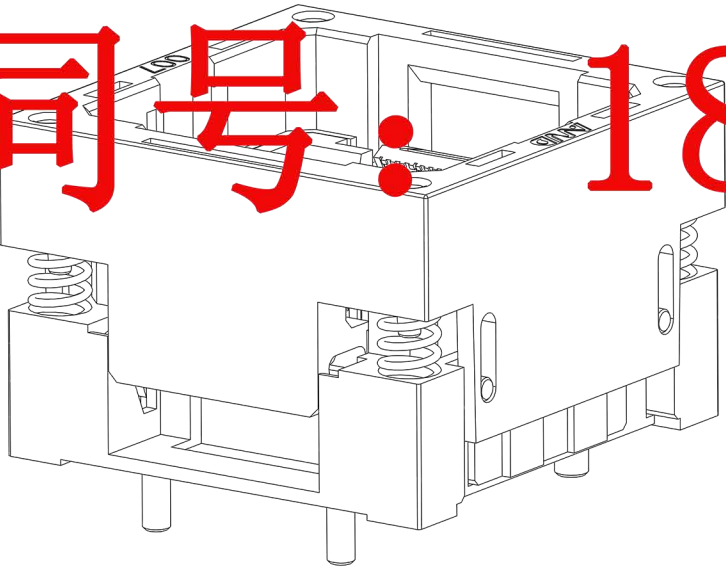
Applicable IC



TOP VIEW

BOTTOM VIEW

SIDE VIEW

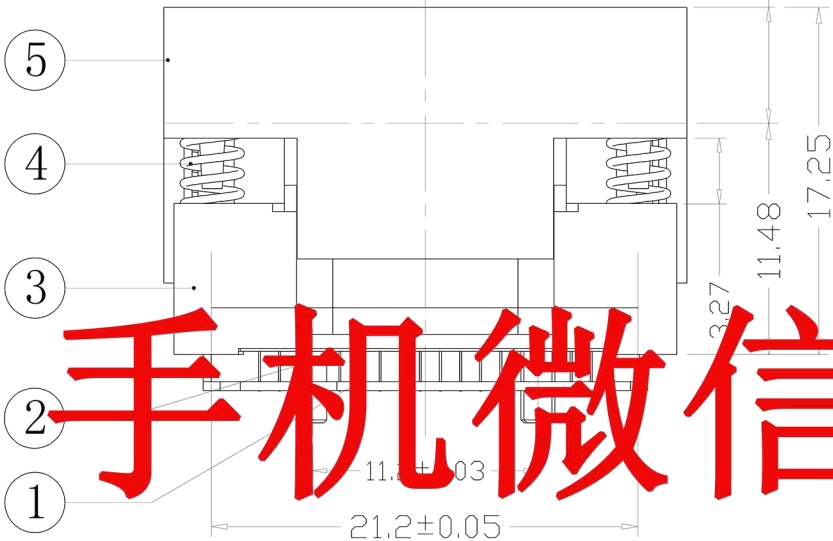
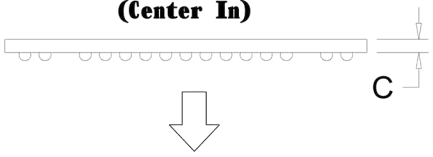


8	310-048-D105D	IC GUIDE	PEI/PES	2	BLACK
7	310-048-C105D	SLIDER	PEI/PES	1	BLACK
6	310-048-C105D	IC HOLDER	PEI/PES	2	BLACK
5	310-048-B105D	COVER	PEI/PES	1	BLACK
4	20-B-4505B	SPRING	SUS	4	FOR COVER
3	310-048-A105D	BASE	PEI/PES	1	BLACK
2	310-048-F105D	LOCATOR	PEI/PES	3	BLACK
1	04-A-1705	CONTACT	BeCu	100	Au PLATING
No	Part Number	Name	Material	Q'ty	Note

PROJECTION		GENERAL TOLERANCES	±0.10	TITLE	BGA10001 SOCKET
DIMENSION:	mm	SCALE:	1:1	CLASS	007-22100E-2101
APP:		DATE:		DRW. NO	007-BGA-1.0-100(26)-11X11-B-01
CHECK:		DATE:			
DEGK:	ENG04	DATE:	20121114		

手机微信同号: 18824309157

IC Loading Direction
(Center In)



PERFORMANCE

1. Insulation Resistance: 1000MΩ Min. At DC 500V
2. Dielectric Withstanding Voltage For 1 Minute At AC 700V
3. Contact Resistance 30mΩ MAX. at 10mA and 20mV MAX.(Initial)
4. Current Rating: 1A max.
5. Operation Temperature -65°C ~+175°C
6. Contact Force 3-5g Per Pin (Normal)
7. Life Span 25,000 Times (Mechanical)
8. Operation Force 2.0 Kg MAX
9. Testing chips with balls of different size or superficial oxidation, even if no ball